

A HIGH DENSITY INTEGRAL TEST PROBE AND FABRICATION  
METHOD

ABSTRACT OF THE DISCLOSURE

A high density integrated test probe and method of fabrication is described. A group of wires are ball bonded to contact locations on the surface of a fan out substrate. The wires are sheared off leaving a stub, the end of which is flattened by an anvil. Before flattening a sheet of material having a group of holes is arranged for alignment with the group of stubs is disposed over the stubs. The sheet of material supports the enlarged tip. The substrate with stubs form a probe which is moved into engagement with contact locations on a work piece such as a drip or packaging substrate.